XN01457

Silicon PNP epitaxial planar type

For general amplification

■ Features

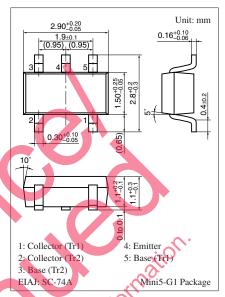
- Two elements incorporated into one package (Emitter-coupled transistors)
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

• 2SB1693 × 2

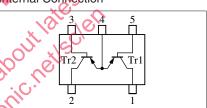
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-40	V	
Collector-emitter voltage (Base open)	V _{CEO}	-20	V	
Emitter-base voltage (Collector open)	V_{EBO}	-15	V	
Collector current	Ic	- 0.5	A	
Peak collector current	I_{CP}	-1	A	
Total power dissipation	P _T	300	mW	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



Marking Symbol:

Internal Connection

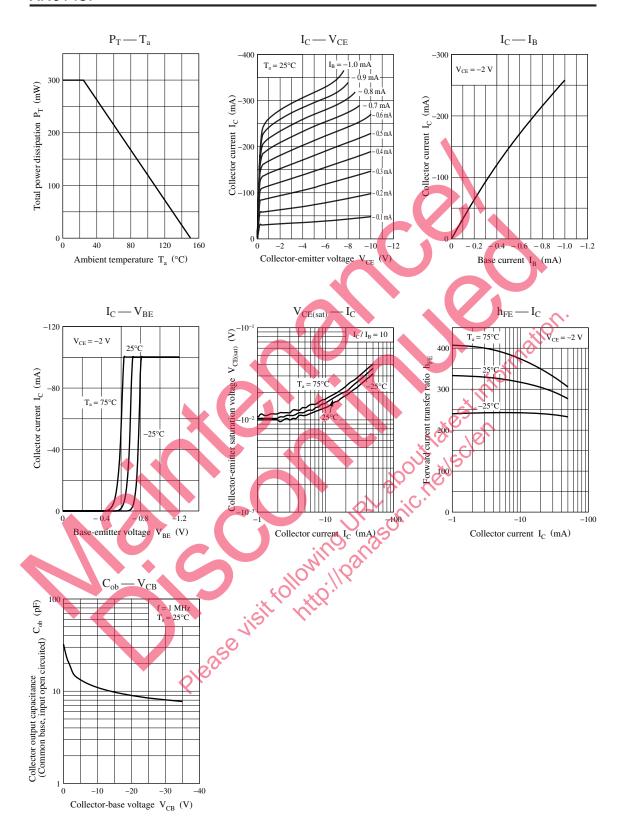


■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \mu A, I_{\rm E} = 0$	-40			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	-20			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \mu A, I_{\rm C} = 0$	-15			V
Forward current transfer ratio *1	h _{FE1}	$V_{CE} = -2 \text{ V}, I_{C} = -100 \text{ mA}$	160		560	_
	Ch _{FE2}	$V_{CE} = -2 \text{ V}, I_{C} = -500 \text{ mA}$	100			
h _{FE} ratio *1, 2	h _{FE(Small}	$V_{CE} = -2 \text{ V}, I_{C} = -100 \text{ mA}$	0.50	0.99		_
	/Large)					
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$		-60	-300	mV
		$I_C = -0.5 \text{ A}, I_B = -25 \text{ mA}$		-210	-500	
Transition frequency	f_T	$V_{CB} = -5 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		170		MHz
Collector output capacitance	Cob	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		16		pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

- 2. *1: Pulse measurement
 - *2: Ratio between 2 elements



2 SJJ00260BED

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